MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

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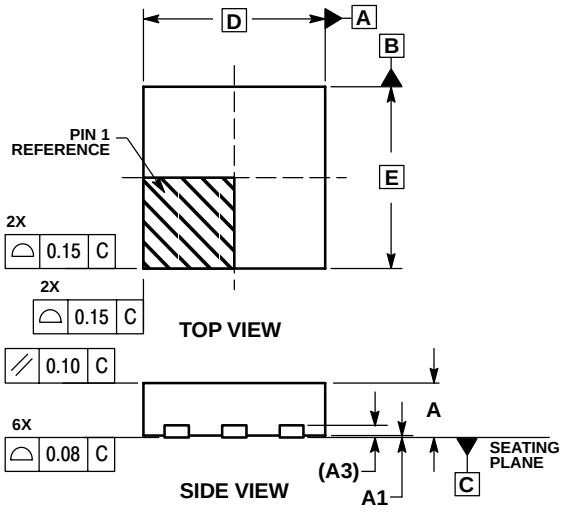
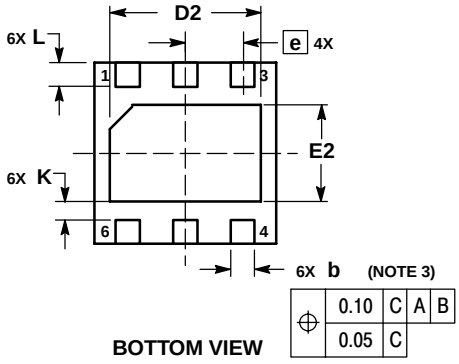
SCALE 2:1

DFN6 3*3 MM, 0.95 PITCH
CASE 506AH−01
ISSUE O

DATE 17 NOV 2004

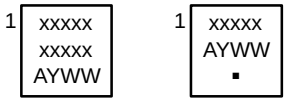




NOTES:
1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMESNION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS		
DIM	MIN	NOM	MAX
A	0.80	0.90	1.00
A1	0.00	0.03	0.05
A3		0.20 REF	
b	0.35	0.40	0.45
D		3.00 BSC	
D2	2.40	2.50	2.60
E		3.00 BSC	
E2	1.50	1.60	1.70
e		0.95 BSC	
K	0.21	−−−	−−−
L	0.30	0.40	0.50

GENERIC MARKING DIAGRAM*

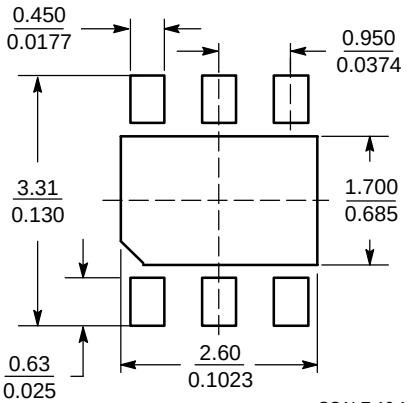


Standard **Pb−Free**

XXXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

SOLDERING FOOTPRINT*



SCALE 10:1 $\left(\frac{\text{mm}}{\text{inches}}\right)$

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	DFN6 3*3 MM, 0.95 PITCH, SINGLE FLAG	PAGE 1 OF 2

ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION. REQ. BY J. CARTER.	17 NOV 2004